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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 8x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c77-10i-l

PIC16C7X

TABLE 3-3: PIC16C74/74A/77 PINOUT DESCRIPTION (Cont'd)

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
RC0/T1OSO/T1CKI	15	16	32	I/O	ST	PORTC is a bi-directional I/O port. RC0 can also be the Timer1 oscillator output or a Timer1 clock input. RC1 can also be the Timer1 oscillator input or Capture2 input/Compare2 output/PWM2 output. RC2 can also be the Capture1 input/Compare1 output/PWM1 output. RC3 can also be the synchronous serial clock input/output for both SPI and I ² C modes. RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode). RC5 can also be the SPI Data Out (SPI mode). RC6 can also be the USART Asynchronous Transmit or Synchronous Clock. RC7 can also be the USART Asynchronous Receive or Synchronous Data.
RC1/T1OSI/CCP2	16	18	35	I/O	ST	
RC2/CCP1	17	19	36	I/O	ST	
RC3/SCK/SCL	18	20	37	I/O	ST	
RC4/SDI/SDA	23	25	42	I/O	ST	
RC5/SDO	24	26	43	I/O	ST	
RC6/TX/CK	25	27	44	I/O	ST	
RC7/RX/DT	26	29	1	I/O	ST	
RD0/PSP0	19	21	38	I/O	ST/TTL ⁽³⁾	PORTD is a bi-directional I/O port or parallel slave port when interfacing to a microprocessor bus.
RD1/PSP1	20	22	39	I/O	ST/TTL ⁽³⁾	
RD2/PSP2	21	23	40	I/O	ST/TTL ⁽³⁾	
RD3/PSP3	22	24	41	I/O	ST/TTL ⁽³⁾	
RD4/PSP4	27	30	2	I/O	ST/TTL ⁽³⁾	
RD5/PSP5	28	31	3	I/O	ST/TTL ⁽³⁾	
RD6/PSP6	29	32	4	I/O	ST/TTL ⁽³⁾	
RD7/PSP7	30	33	5	I/O	ST/TTL ⁽³⁾	
RE0/RD \bar{D} /AN5	8	9	25	I/O	ST/TTL ⁽³⁾	PORTE is a bi-directional I/O port. RE0 can also be read control for the parallel slave port, or analog input5. RE1 can also be write control for the parallel slave port, or analog input6. RE2 can also be select control for the parallel slave port, or analog input7.
RE1/WR \bar{R} /AN6	9	10	26	I/O	ST/TTL ⁽³⁾	
RE2/CS \bar{S} /AN7	10	11	27	I/O	ST/TTL ⁽³⁾	
Vss	12,31	13,34	6,29	P	—	Ground reference for logic and I/O pins.
VDD	11,32	12,35	7,28	P	—	Positive supply for logic and I/O pins.
NC	—	1,17,28,40	12,13,33,34		—	These pins are not internally connected. These pins should be left unconnected.

Legend: I = input O = output I/O = input/output P = power
 — = Not used TTL = TTL input ST = Schmitt Trigger input

- Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.
 2: This buffer is a Schmitt Trigger input when used in serial programming mode.
 3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
 4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

PIC16C7X

NOTES:

PIC16C7X

NOTES:

PIC16C7X

5.3 PORTC and TRISC Registers

Applicable Devices							
72	73	73A	74	74A	76	77	

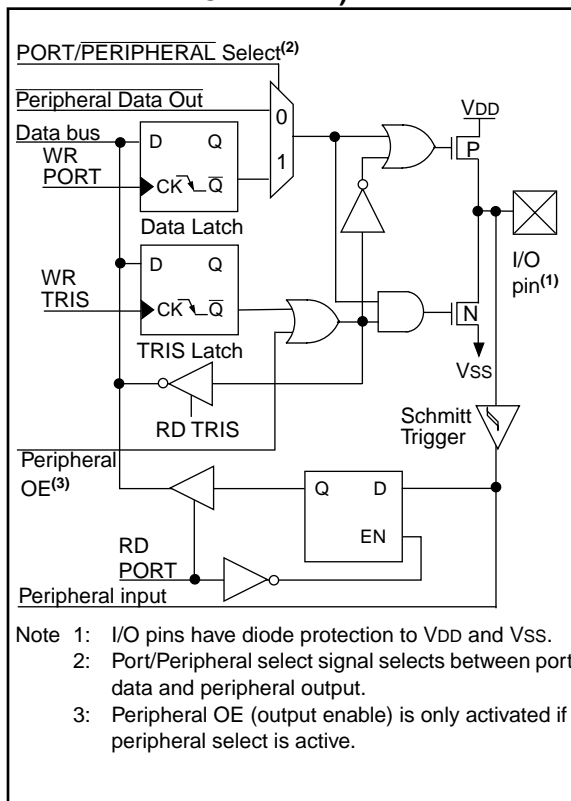
PORTC is an 8-bit bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (BSF, BCF, XORWF) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 5-3: INITIALIZING PORTC

```
BCF    STATUS, RP0    ; Select Bank 0
BCF    STATUS, RP1    ; PIC16C76/77 only
CLRF   PORTC          ; Initialize PORTC by
                        ; clearing output
                        ; data latches
BSF    STATUS, RP0    ; Select Bank 1
MOVLW  0xCF           ; Value used to
                        ; initialize data
                        ; direction
MOVWF  TRISC          ; Set RC<3:0> as inputs
                        ; RC<5:4> as outputs
                        ; RC<7:6> as inputs
```

FIGURE 5-6: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE)



- Note 1: I/O pins have diode protection to VDD and VSS.
 Note 2: Port/Peripheral select signal selects between port data and peripheral output.
 Note 3: Peripheral OE (output enable) is only activated if peripheral select is active.

TABLE 5-5: PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input
RC1/T1OSI/CCP2 ⁽¹⁾	bit1	ST	Input/output port pin or Timer1 oscillator input or Capture2 input/Compare2 output/PWM2 output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I ² C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output
RC6/TX/CK ⁽²⁾	bit6	ST	Input/output port pin or USART Asynchronous Transmit, or USART Synchronous Clock
RC7/RX/DT ⁽²⁾	bit7	ST	Input/output port pin or USART Asynchronous Receive, or USART Synchronous Data

Legend: ST = Schmitt Trigger input

Note 1: The CCP2 multiplexed function is not enabled on the PIC16C72.

Note 2: The TX/CK and RX/DT multiplexed functions are not enabled on the PIC16C72.

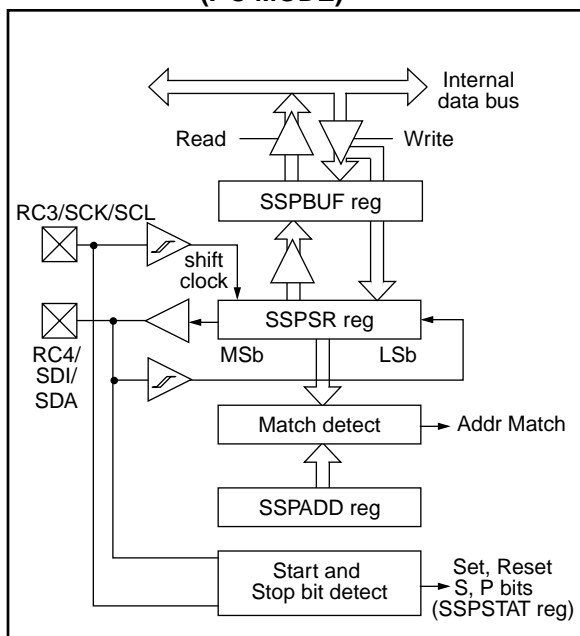
PIC16C7X

NOTES:

11.5 SSP I²C Operation

The SSP module in I²C mode fully implements all slave functions, except general call support, and provides interrupts on start and stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing. Two pins are used for data transfer. These are the RC3/SCK/SCL pin, which is the clock (SCL), and the RC4/SDI/SDA pin, which is the data (SDA). The user must configure these pins as inputs or outputs through the TRISC<4:3> bits. The SSP module functions are enabled by setting SSP Enable bit SSPEN (SSPCON<5>).

FIGURE 11-24: SSP BLOCK DIAGRAM (I²C MODE)



The SSP module has five registers for I²C operation. These are the:

- SSP Control Register (SSPCON)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) - Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I²C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address), with start and stop bit interrupts enabled
- I²C Slave mode (10-bit address), with start and stop bit interrupts enabled
- I²C Firmware controlled Master Mode, slave is idle

Selection of any I²C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open drain, provided these pins are programmed to inputs by setting the appropriate TRISC bits.

The SSPSTAT register gives the status of the data transfer. This information includes detection of a START or STOP bit, specifies if the received byte was data or address if the next byte is the completion of 10-bit address, and if this will be a read or write data transfer. The SSPSTAT register is read only.

The SSPBUF is the register to which transfer data is written to or read from. The SSPSR register shifts the data in or out of the device. In receive operations, the SSPBUF and SSPSR create a doubled buffered receiver. This allows reception of the next byte to begin before reading the last byte of received data. When the complete byte is received, it is transferred to the SSPBUF register and flag bit SSPIF is set. If another complete byte is received before the SSPBUF register is read, a receiver overflow has occurred and bit SSPOV (SSPCON<6>) is set and the byte in the SSPSR is lost.

The SSPADD register holds the slave address. In 10-bit mode, the user first needs to write the high byte of the address (1111 0 A9 A8 0). Following the high byte address match, the low byte of the address needs to be loaded (A7:A0).

11.5.2 MASTER MODE

Master mode of operation is supported in firmware using interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a reset or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the I²C bus may be taken when the P bit is set, or the bus is idle and both the S and P bits are clear.

In master mode the SCL and SDA lines are manipulated by clearing the corresponding TRISC<4:3> bit(s). The output level is always low, irrespective of the value(s) in PORTC<4:3>. So when transmitting data, a '1' data bit must have the TRISC<4> bit set (input) and a '0' data bit must have the TRISC<4> bit cleared (output). The same scenario is true for the SCL line with the TRISC<3> bit.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received

Master mode of operation can be done with either the slave mode idle (SSPM3:SSPM0 = 1011) or with the slave active. When both master and slave modes are enabled, the software needs to differentiate the source(s) of the interrupt.

11.5.3 MULTI-MASTER MODE

In multi-master mode, the interrupt generation on the detection of the START and STOP conditions allows the determination of when the bus is free. The STOP (P) and START (S) bits are cleared from a reset or when the SSP module is disabled. The STOP (P) and START (S) bits will toggle based on the START and STOP conditions. Control of the I²C bus may be taken when bit P (SSPSTAT<4>) is set, or the bus is idle and both the S and P bits clear. When the bus is busy, enabling the SSP Interrupt will generate the interrupt when the STOP condition occurs.

In multi-master operation, the SDA line must be monitored to see if the signal level is the expected output level. This check only needs to be done when a high level is output. If a high level is expected and a low level is present, the device needs to release the SDA and SCL lines (set TRISC<4:3>). There are two stages where this arbitration can be lost, these are:

- Address Transfer
- Data Transfer

When the slave logic is enabled, the slave continues to receive. If arbitration was lost during the address transfer stage, communication to the device may be in progress. If addressed an $\overline{\text{ACK}}$ pulse will be generated. If arbitration was lost during the data transfer stage, the device will need to re-transfer the data at a later time.

TABLE 11-5: REGISTERS ASSOCIATED WITH I²C OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other resets
0Bh, 8Bh, 10Bh, 18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
93h	SSPADD	Synchronous Serial Port (I ² C mode) Address Register								0000 0000	0000 0000
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP ⁽²⁾	CKE ⁽²⁾	D/ $\overline{\text{A}}$	P	S	R/ $\overline{\text{W}}$	UA	BF	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.

Shaded cells are not used by SSP module in SPI mode.

Note 1: PSPIF and PSPIE are reserved on the PIC16C73/73A/76, always maintain these bits clear.

Note 2: The SMP and CKE bits are implemented on the PIC16C76/77 only. All other PIC16C7X devices have these two bits unimplemented, read as '0'.

14.3 Reset

Applicable Devices					
72	73	73A	74	74A	76/77

The PIC16CXX differentiates between various kinds of reset:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ reset during normal operation
- $\overline{\text{MCLR}}$ reset during SLEEP
- WDT Reset (normal operation)
- Brown-out Reset (BOR) (PIC16C72/73A/74A/76/77)

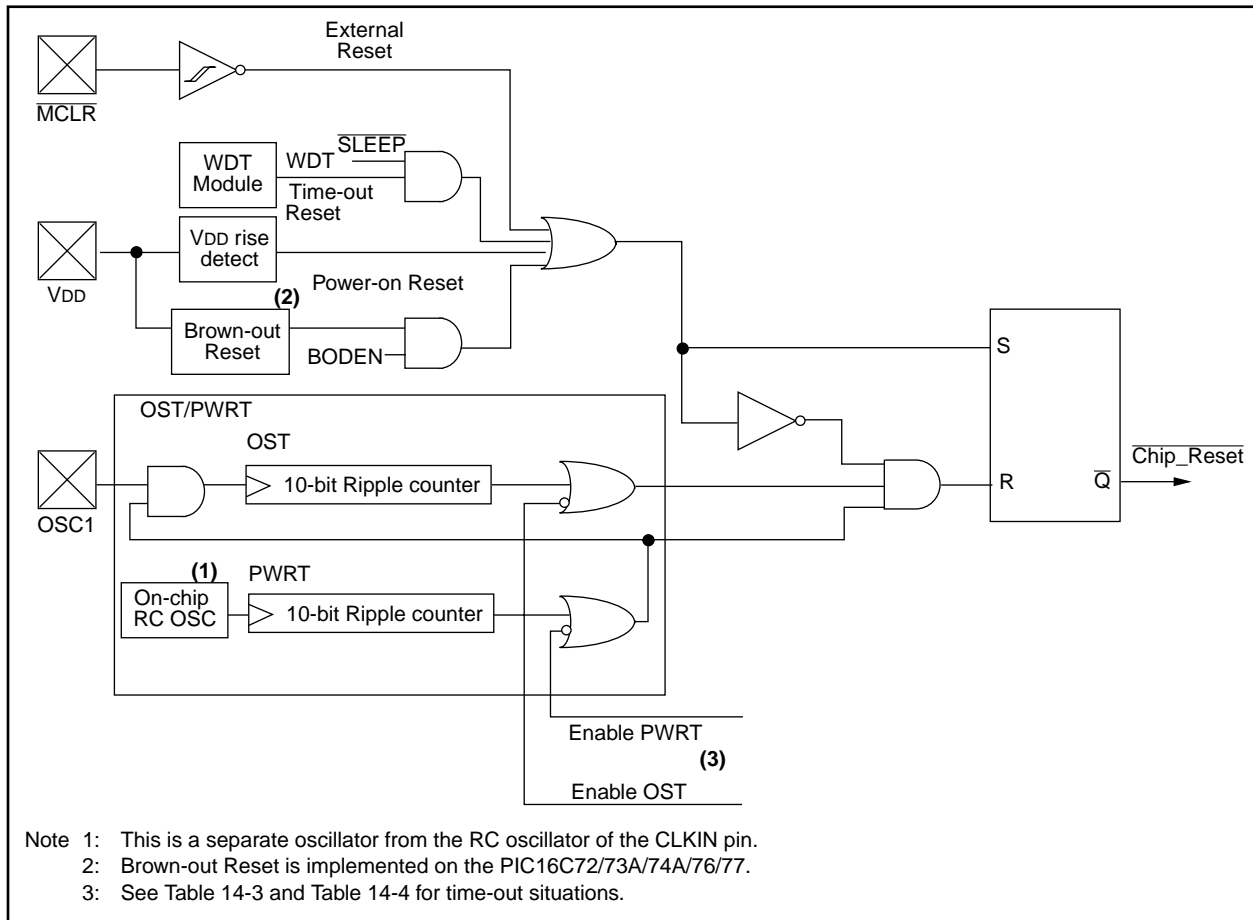
Some registers are not affected in any reset condition; their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-on Reset (POR), on the $\overline{\text{MCLR}}$ and WDT Reset, on $\overline{\text{MCLR}}$ reset during SLEEP, and Brown-out Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation. The TO and PD bits are set or cleared differently in different reset situations as indicated in Table 14-5 and Table 14-6. These bits are used in software to determine the nature of the reset. See Table 14-8 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 14-8.

The PIC16C72/73A/74A/76/77 have a $\overline{\text{MCLR}}$ noise filter in the $\overline{\text{MCLR}}$ reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{\text{MCLR}}$ pin low.

FIGURE 14-8: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



14.8 Power-down Mode (SLEEP)

Applicable Devices							
72	73	73A	74	74A	76	77	

Power-down mode is entered by executing a **SLEEP** instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the \overline{PD} bit (STATUS<3>) is cleared, the \overline{TO} (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before the **SLEEP** instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD} , or V_{SS} , ensure no external circuitry is drawing current from the I/O pin, power-down the A/D, disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The \overline{TOCKI} input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The \overline{MCLR} pin must be at a logic high level (V_{IHMC}).

14.8.1 WAKE-UP FROM SLEEP

The device can wake up from **SLEEP** through one of the following events:

1. External reset input on \overline{MCLR} pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from INT pin, RB port change, or some Peripheral Interrupts.

External \overline{MCLR} Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device reset. The \overline{PD} bit, which is set on power-up, is cleared when **SLEEP** is invoked. The \overline{TO} bit is cleared if a WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from **SLEEP**:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. SSP (Start/Stop) bit detect interrupt.
3. SSP transmit or receive in slave mode (SPI/I²C).
4. CCP capture mode interrupt.
5. Parallel Slave Port read or write.
6. A/D conversion (when A/D clock source is RC).
7. Special event trigger (Timer1 in asynchronous mode using an external clock).
8. USART TX or RX (synchronous slave mode).

Other peripherals cannot generate interrupts since during **SLEEP**, no on-chip Q clocks are present.

When the **SLEEP** instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the **SLEEP** instruction. If the GIE bit is set (enabled), the device executes the instruction after the **SLEEP** instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following **SLEEP** is not desirable, the user should have a **NOP** after the **SLEEP** instruction.

14.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a **SLEEP** instruction, the **SLEEP** instruction will complete as a **NOP**. Therefore, the WDT and WDT postscaler will not be cleared, the \overline{TO} bit will not be set and \overline{PD} bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a **SLEEP** instruction, the device will immediately wake up from sleep. The **SLEEP** instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the \overline{TO} bit will be set and the \overline{PD} bit will be cleared.

Even if the flag bits were checked before executing a **SLEEP** instruction, it may be possible for flag bits to become set before the **SLEEP** instruction completes. To determine whether a **SLEEP** instruction executed, test the \overline{PD} bit. If the \overline{PD} bit is set, the **SLEEP** instruction was executed as a **NOP**.

To ensure that the WDT is cleared, a **CLRWDT** instruction should be executed before a **SLEEP** instruction.

17.5 Timing Diagrams and Specifications

FIGURE 17-2: EXTERNAL CLOCK TIMING

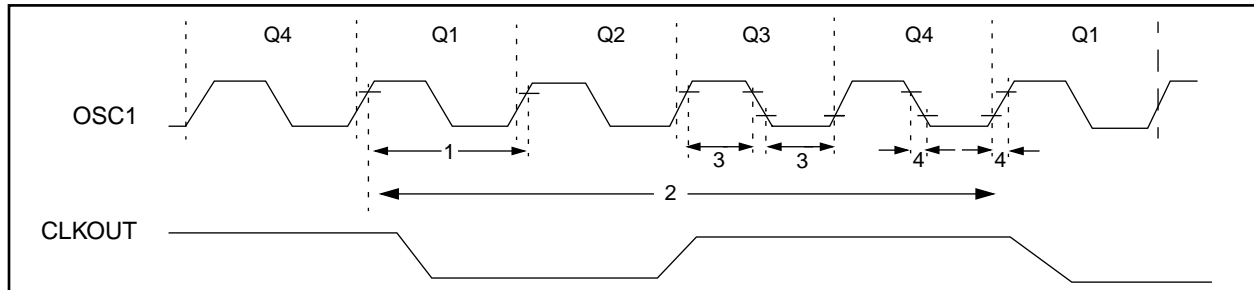


TABLE 17-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
	Tosc	Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
2	TCY	Instruction Cycle Time (Note 1)	200	—	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 17-8: SPI MODE TIMING

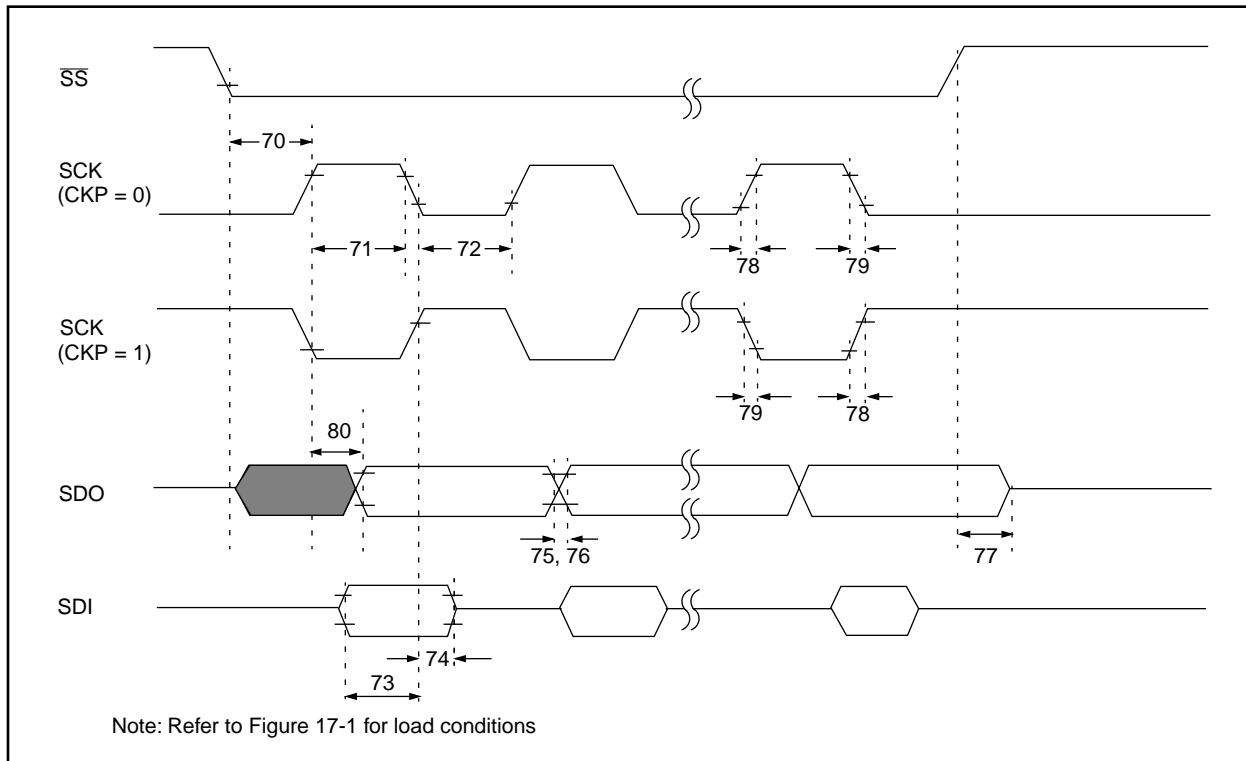


TABLE 17-7: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK \downarrow or SCK \uparrow input	T _{CY}	—	—	ns	
71	TscH	SCK input high time (slave mode)	T _{CY} + 20	—	—	ns	
72	TscL	SCK input low time (slave mode)	T _{CY} + 20	—	—	ns	
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74	Tsch2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75	TdoR	SDO data output rise time	—	10	25	ns	
76	TdoF	SDO data output fall time	—	10	25	ns	
77	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance	10	—	50	ns	
78	TscR	SCK output rise time (master mode)	—	10	25	ns	
79	TscF	SCK output fall time (master mode)	—	10	25	ns	
80	Tsch2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C7X

Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 18-9: I²C BUS START/STOP BITS TIMING

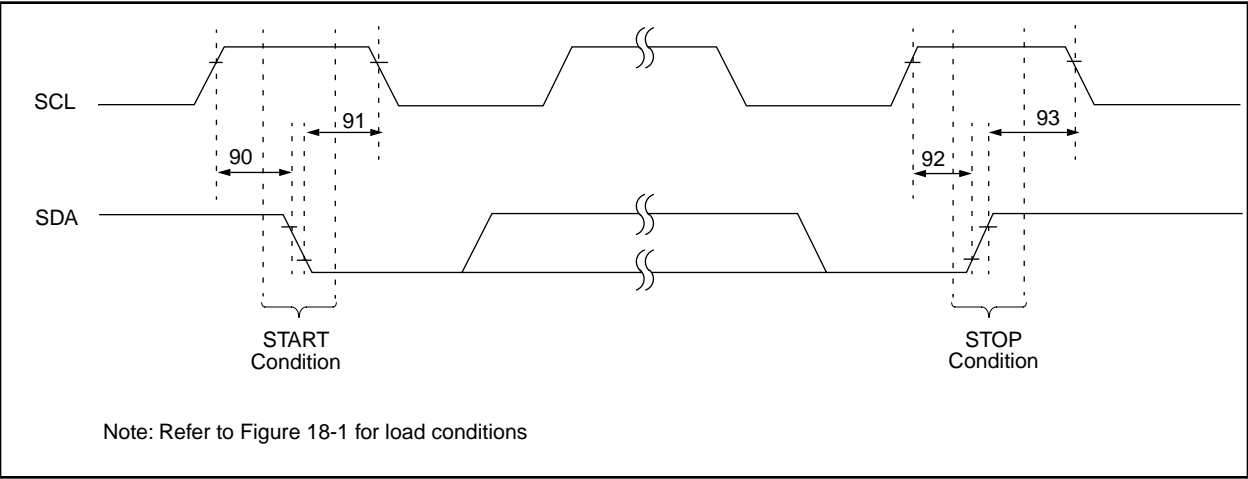


TABLE 18-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
		Setup time	400 kHz mode	600	—	—		
91	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
		Hold time	400 kHz mode	600	—	—		
92	TSU:STO	STOP condition	100 kHz mode	4700	—	—	ns	
		Setup time	400 kHz mode	600	—	—		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns	
		Hold time	400 kHz mode	600	—	—		

20.0 ELECTRICAL CHARACTERISTICS FOR PIC16C76/77

Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$, and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0 to +14V
Voltage on RA4 with respect to VSS	0 to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, I _{IK} (V _I < 0 or V _I > VDD)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3)	200 mA
Maximum current sunk by PORTC and PORTD (combined) (Note 3)	200 mA
Maximum current sourced by PORTC and PORTD (combined) (Note 3)	200 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

Note 2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

Note 3: PORTD and PORTE are not implemented on the PIC16C76.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIC16C7X

Applicable Devices 72 73 73A 74 74A 76 77

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 20.1 and Section 20.2.							
DC CHARACTERISTICS							
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
D090	Output High Voltage I/O ports (Note 3)	VOH	VDD - 0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
D090A			VDD - 0.7	-	-	V	
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	-	-	V	
D092A			VDD - 0.7	-	-	V	
D150*	Open-Drain High Voltage	VOD	-	-	14	V	RA4 pin
	Capacitive Loading Specs on Output Pins						
D100	OSC2 pin	COSC2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	CIO	-	-	50	pF	
D102	SCL, SDA in I ² C mode	CB	-	-	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.
- 2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3: Negative current is defined as current sourced by the pin.

PIC16C7X

Applicable Devices 72 73 73A 74 74A 76 77

20.5 Timing Diagrams and Specifications

FIGURE 20-2: EXTERNAL CLOCK TIMING

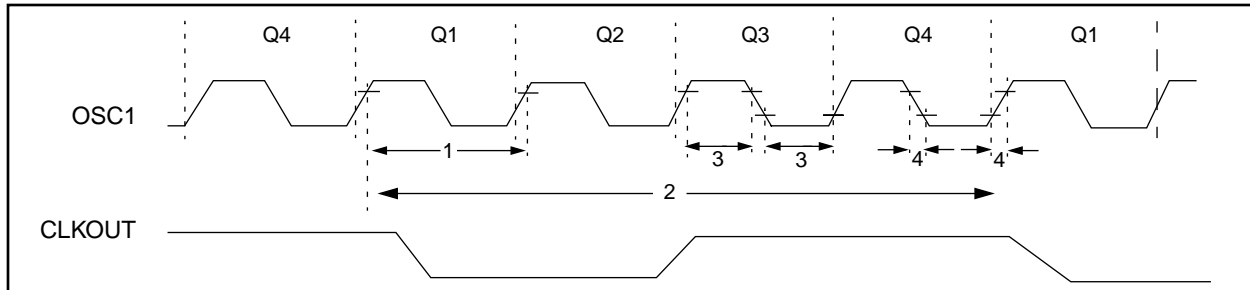


TABLE 20-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
	1	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
2	Tcy	Instruction Cycle Time (Note 1)	200	Tcy	DC	ns	Tcy = 4/Fosc
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

PIC16C7X

Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 21-16: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

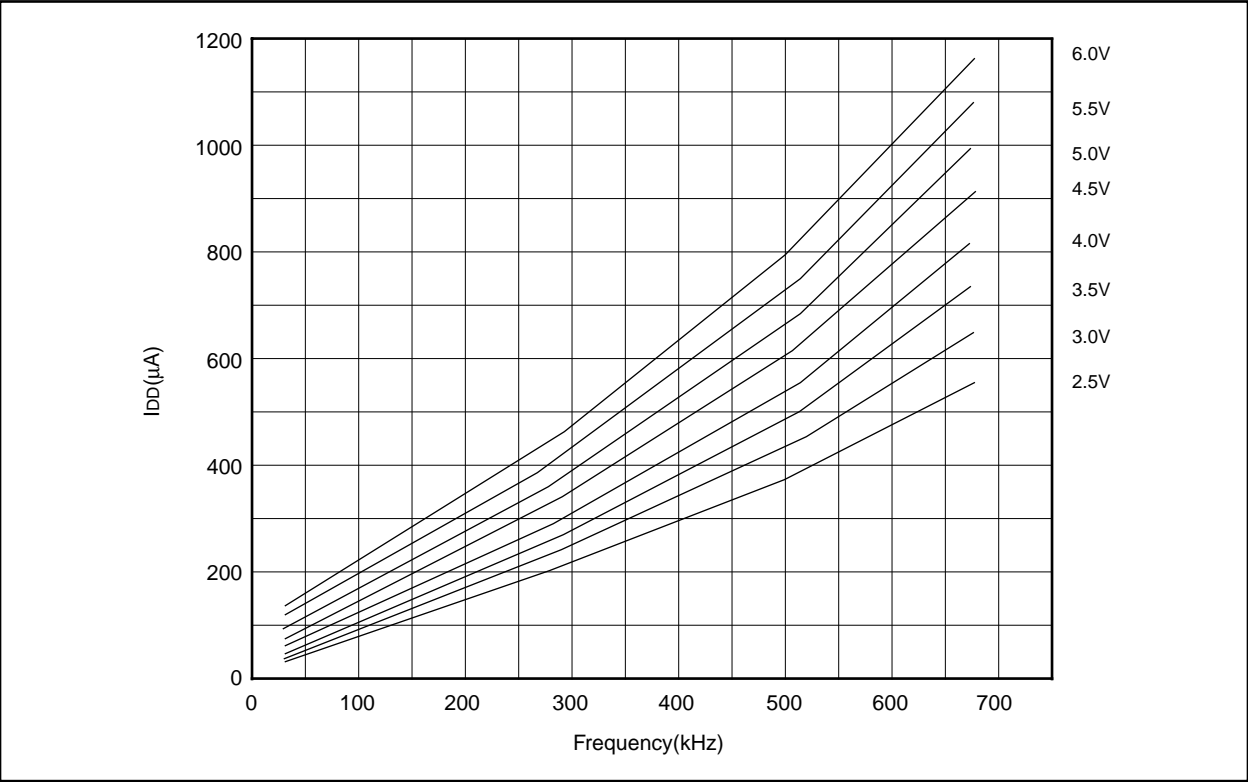
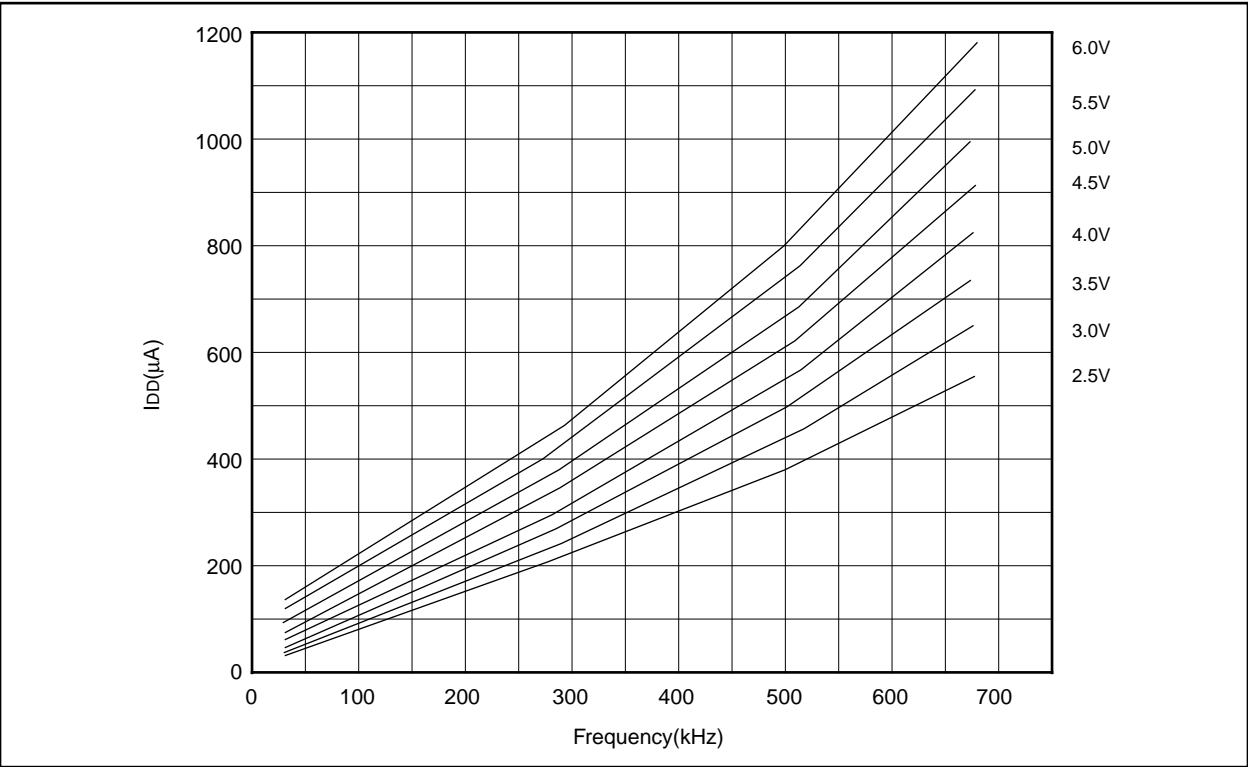
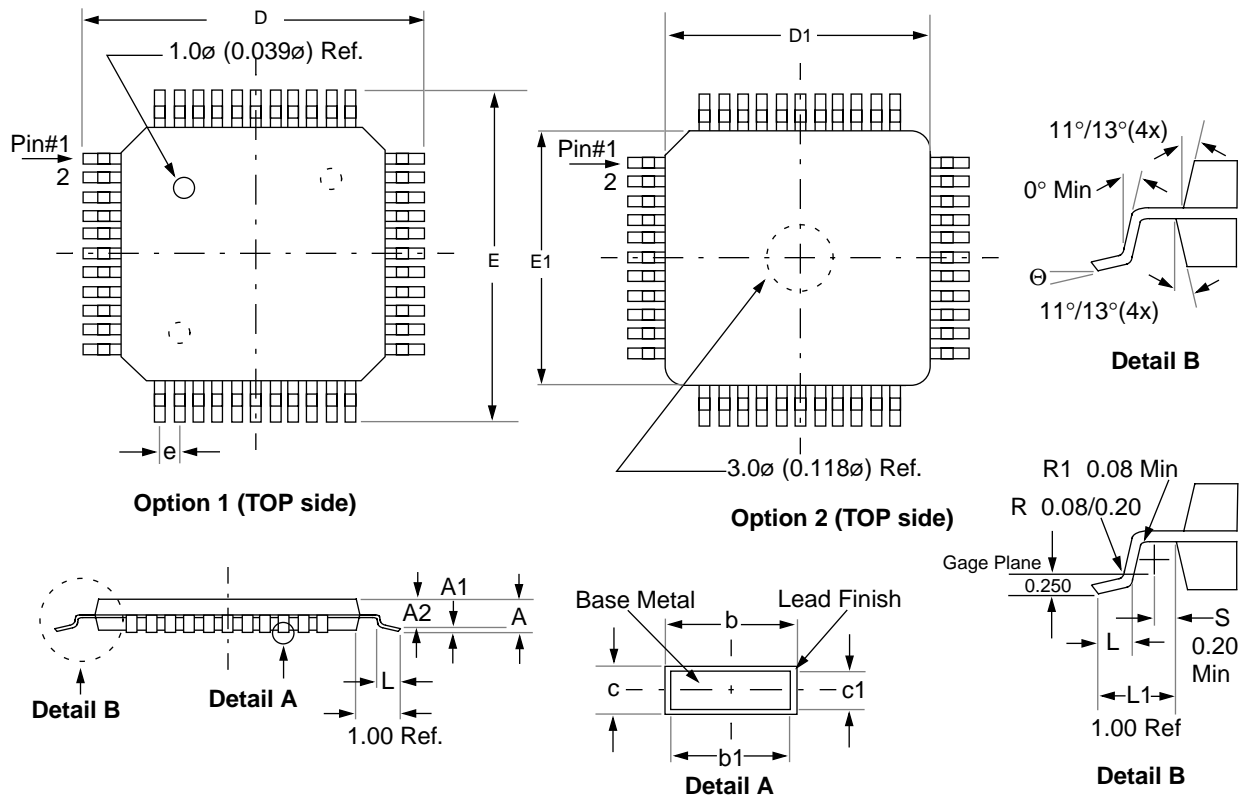


FIGURE 21-17: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

22.9 44-Lead Plastic Surface Mount (TQFP 10x10 mm Body 1.0/0.10 mm Lead Form) (TQ)



Package Group: Plastic TQFP						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
A	1.00	1.20		0.039	0.047	
A1	0.05	0.15		0.002	0.006	
A2	0.95	1.05		0.037	0.041	
D	11.75	12.25		0.463	0.482	
D1	9.90	10.10		0.390	0.398	
E	11.75	12.25		0.463	0.482	
E1	9.90	10.10		0.390	0.398	
L	0.45	0.75		0.018	0.030	
e	0.80 BSC			0.031 BSC		
b	0.30	0.45		0.012	0.018	
b1	0.30	0.40		0.012	0.016	
c	0.09	0.20		0.004	0.008	
c1	0.09	0.16		0.004	0.006	
N	44	44		44	44	
Θ	0°	7°		0°	7°	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25mm (0.010") per side. D1 and E1 dimensions including mold mismatch.

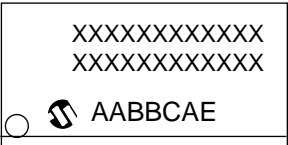
2: Dimension "b" does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08mm (0.003") max.

3: This outline conforms to JEDEC MS-026.

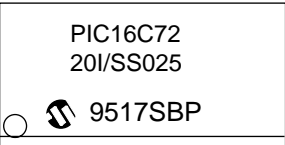
PIC16C7X

22.10 Package Marking Information

28-Lead SSOP



Example



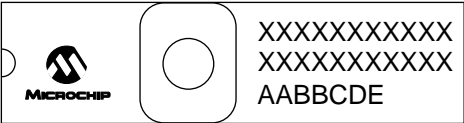
28-Lead PDIP (Skinny DIP)



Example



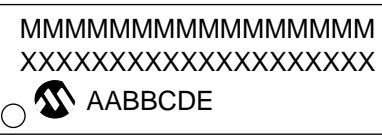
28-Lead Side Brazed Skinny Windowed



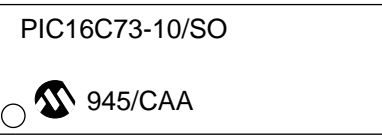
Example



28-Lead SOIC



Example



Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calender year)
	BB	Week code (week of January 1 is week '01')
	C	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D ₁	Mask revision number for microcontroller
	E	Assembly code of the plant or country of origin in which part was assembled.
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.		

* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

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